

3.0x2.0mm SURFACE MOUNT LED LAMP

# PRELIMINARY SPEC

### Features

- 3.0mm x 2.0mm, 1.4mm high, only minimum
- Space required.
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.

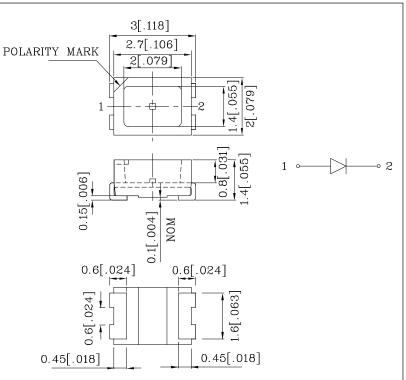


Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Rating (TA=25°C)	M2NW (InGaN)	Unit	
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	100	mA
Power Dissipation	Рт	111	mW
Operating Temperature	ТА	$-40 \sim +85$	°C
Storage Temperature Tstg		$-40 \sim +85$	C
Electrostatic Discharge Three	shold (HBM)	1000	V



Operating Characteristic (TA=25°C)	M2NW (InGaN)	Unit	
Forward Voltage (Typ.) (IF=20mA)	VF	3.2	V
Forward Voltage (Max.) (IF=20mA)	VF	3.7	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Chromaticity Coordinates (Typ.)	х	0.31	
	Y	0.31	
Capacitance (Typ.) (VF=0V, f=1MHz)	С	110	pF

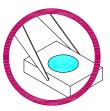
Part Number	Emitting Color	Emitting Material	Lens-color		Inter (IF=2	inous nsity 20mA) cd	Viewing Angle 2 0 1/2
					min.	typ.	
XZM2NW50FS	White	InGaN	Water Clea	r	480	1195	120°
Published Date : AUG	25, 2008	Drawing No : XI	OSB1330	V4	Checked :	B.L.LIU	P.1/6



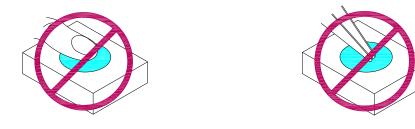
## **Handling Precautions**

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

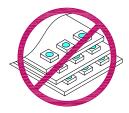
1. Handle the component along the side surfaces by using forceps or appropriate tools.



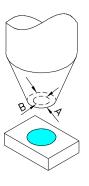
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

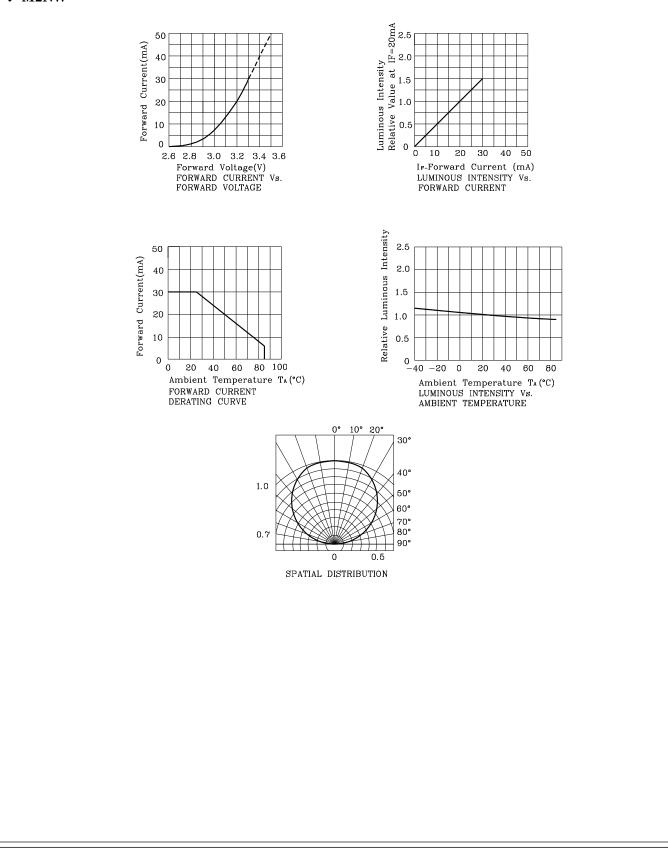


P.2/6



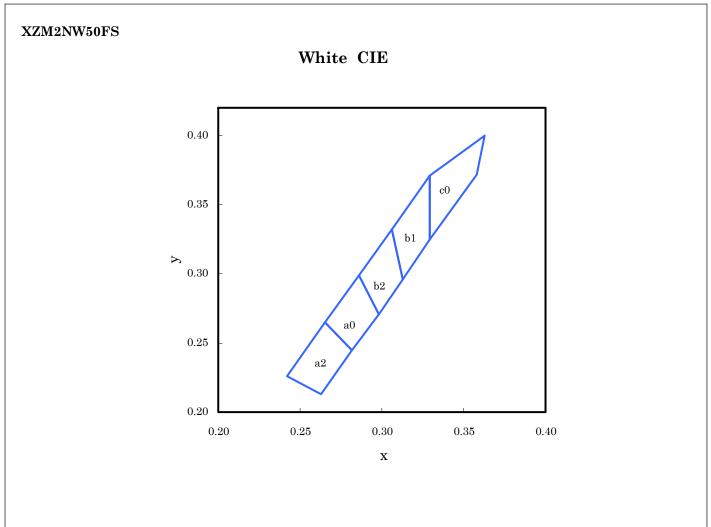
# Part Number: XZM2NW50FS 3.0x2.0mm SURFACE MOUNT LED LAMP

## ♦ M2NW



V4





Rank a2				
Х	0.263	0.282	0.265	0.242
Y	0.213	0.245	0.265	0.226

Rank a0					
Х	0.282	0.298	0.286	0.265	
Y	0.245	0.271	0.299	0.265	

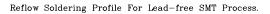
Rank b2					
Х	0.298	0.313	0.306	0.286	
Y	0.271	0.296	0.332	0.299	

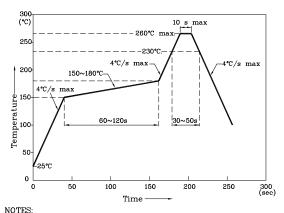
Rank c0				
Х	0.329	0.358	0.363	0.329
Y	0.325	0.372	0.400	0.371

Rank b1					
Х	0.313	0.329	0.329	0.306	
Y	0.296	0.325	0.371	0.332	

V4





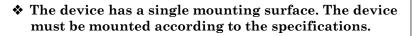


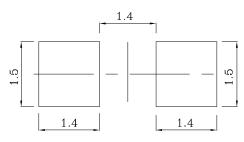
1. Maximum soldering temperature should not exceed 260°c.

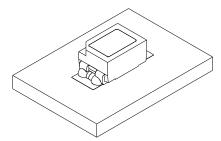
2. Recommended reflow temperature: 145°c-260°c.

3. Do not put stress to the epoxy resin during high

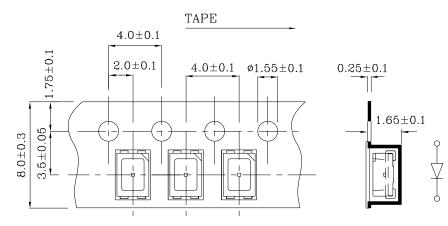
- temperatures conditions.
- Recommended Soldering Pattern (Units : mm; Tolerance: ±0.1)







## Tape Specification (Units : mm)



#### Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or chromaticity), the typical accuracy of the sorting process is as follows:

1. 1. Measurement tolerance of the chromaticity coordinates is  $\pm 0.01$ .

2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



